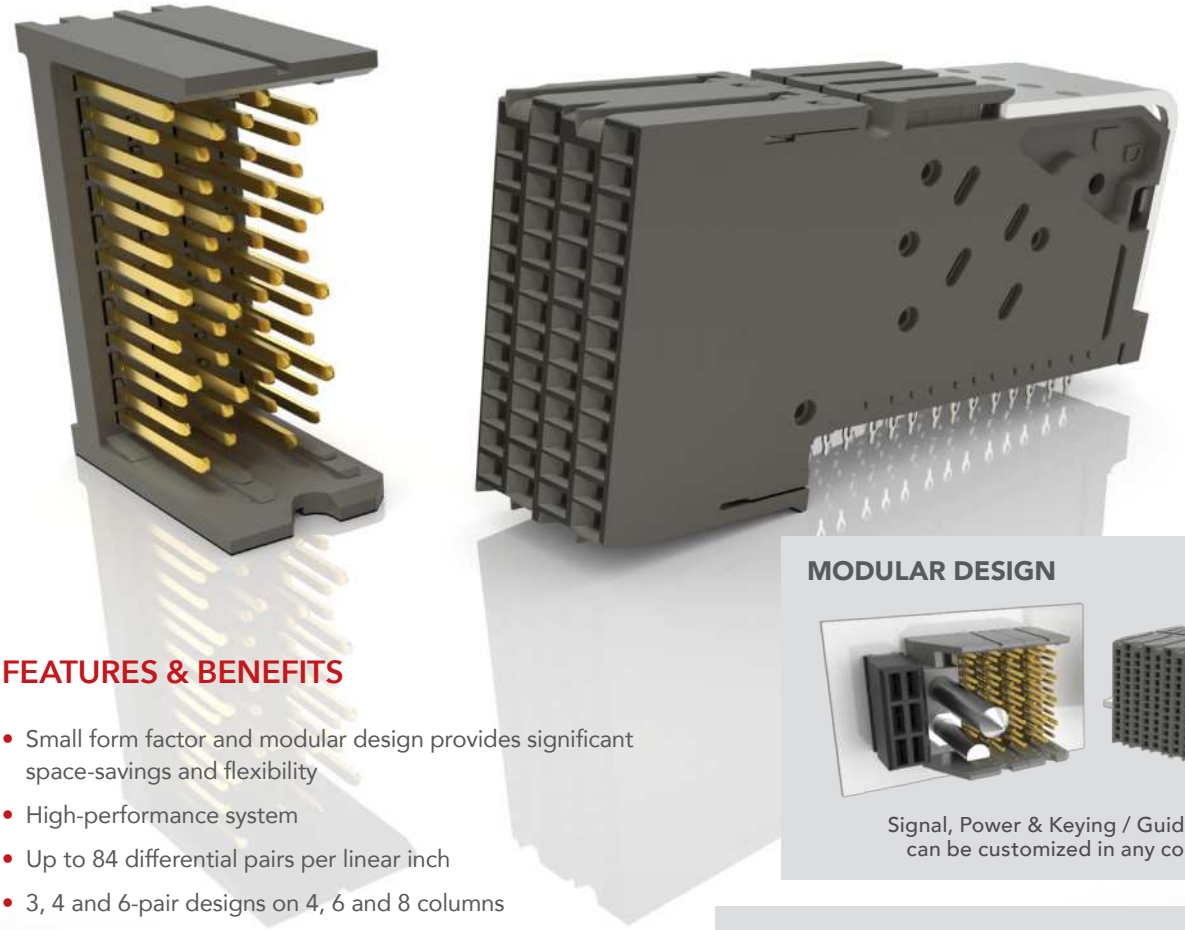
XCede® HD

HIGH-DENSITY BACKPLANE HEADERS & SOCKETS

(1.80 mm) .071" PITCH

16 Gbps



FEATURES & BENEFITS

- Small form factor and modular design provides significant space-savings and flexibility
- High-performance system
- Up to 84 differential pairs per linear inch
- 3, 4 and 6-pair designs on 4, 6 and 8 columns
- Integrated power, guidance, keying and side walls available
- 85 Ω and 100 Ω options
- Combine any configuration of modules to create one integrated receptacle (BSP Series); corresponding terminal modules are individually mounted to the backplane. Visit **samtec.com?BSP** or contact **HSBP@samtec.com**
- Press-fit extraction and insertion tool options; please visit **samtec.com/tooling** for details

MODULAR DESIGN

Signal, Power & Keying / Guidance options can be customized in any configuration

HIGH-DENSITY, SMALL FORM FACTOR



XCede® HD
Up to 84 pairs per linear inch

Traditional Backplane
Up to 76 pairs per linear inch

(Both shown with six 4-pair, 8 column receptacles)

KEY SPECIFICATIONS

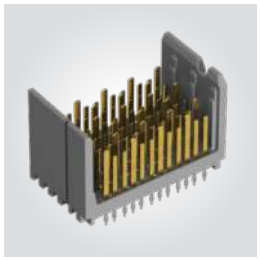
SERIES	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING
HDTM/HDTF	LCP	Phosphor Bronze (HDTM) Copper Alloy (HDTF)	Au or Sn over 50 µ" (1.27 µm) Ni	-40 °C to + 105 °C	1.5 A per contact	48 VAC/ /68 VDC
HPTS/HPTT	LCP	Copper Alloy	Au or Sn over 50 µ" (1.27 µm) Ni	-40 °C to + 105 °C	10 A per blade	48 VAC/ /68 VDC

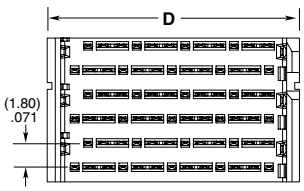
Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.

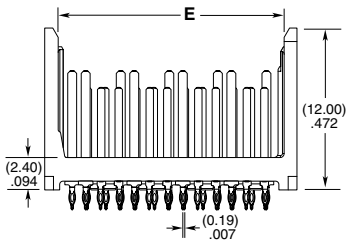
HDTM	PAIRS	NO. OF COLUMNS	TAIL SIZE	S	VT	SIDE WALLS	GUIDANCE	STAGE COMBO	KEYING
	–3, –4, –6 =Pairs Per Column	**–04, –06, –08**	**–1** =(.4495 mm) .0177" Drill **–2** =(.5511 mm) .0217" Drill			**–0** = Open (No Walls) **–1** = Left **–2** = Right **–4** = Left Polarizing with left guidance (–4 Pairs N/A) **–5** = Right Polarizing with right guidance (–4 Pairs N/A)	–4 or –5 Polarizing Only; Leave Blank for No Guidance **–L** = Left Side Guide Pin (–4 Pairs N/A) **–R** = Right Side Guide Pin (–4 Pairs N/A)	**–1** = 3 mm Wipe Signal / 4 mm Wipe Ground **–2** = 2 mm Wipe Signal / 4 mm Wipe Ground **–3** = 3 mm Wipe Signal / 3 mm Wipe Ground **–4** = 2 mm Wipe Signal / 3 mm Wipe Ground **–5** = 2 mm Wipe Signal / 2 mm Wipe Ground	–4 or –5 Polarizing Only; Leave Blank for No Keying **–A thru –H** = Position of Flat on Key (See Table)

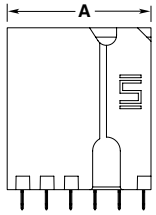
HDTM

Board Mates:
HDTF, BSP





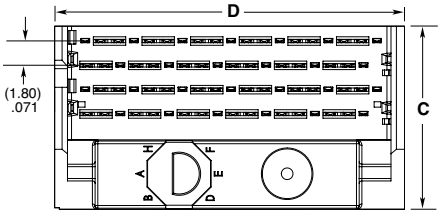


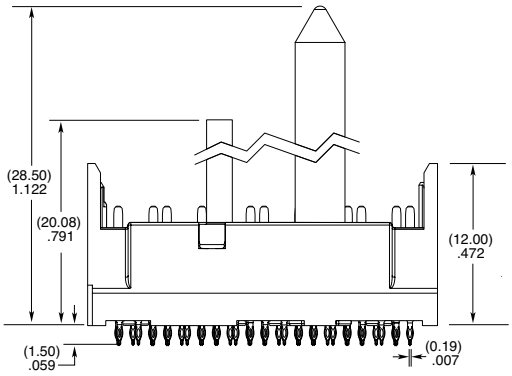


HDTM-4-06-1-S-VT-0-1 SHOWN

NO. OF COLUMNS	A			C	
	No Walls	Left Wall	Right Wall	Left Polarize	Right Polarize
–04	(7.06) .278	(8.20) .323	(8.06) .317	N/A	N/A
–06	(10.66) .420	(11.80) .465	(11.66) .459	(17.14) .675	(16.65) .656
–08	(14.26) .561	(15.40) .606	(15.26) .600	(20.74) .817	(20.25) .797

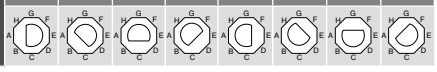
PAIRS PER COLUMN	D	E
	Standard Wall	
–03	(15.10) .594	(13.15) .518
–04	(18.70) .736	(16.75) .659
–06	(25.90) 1.020	(23.95) .943





HDTM-6-04-X-X-VT-4-L-X-A SHOWN

KEYING

–L / –R	–A	–B	–C	–D	–E	–F	–G	–H
								

Notes:
Some lengths, styles and options are non-standard, non-returnable.

XCede® is a registered trademark of Amphenol.

View complete specifications at: samtec.com?HDTM

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